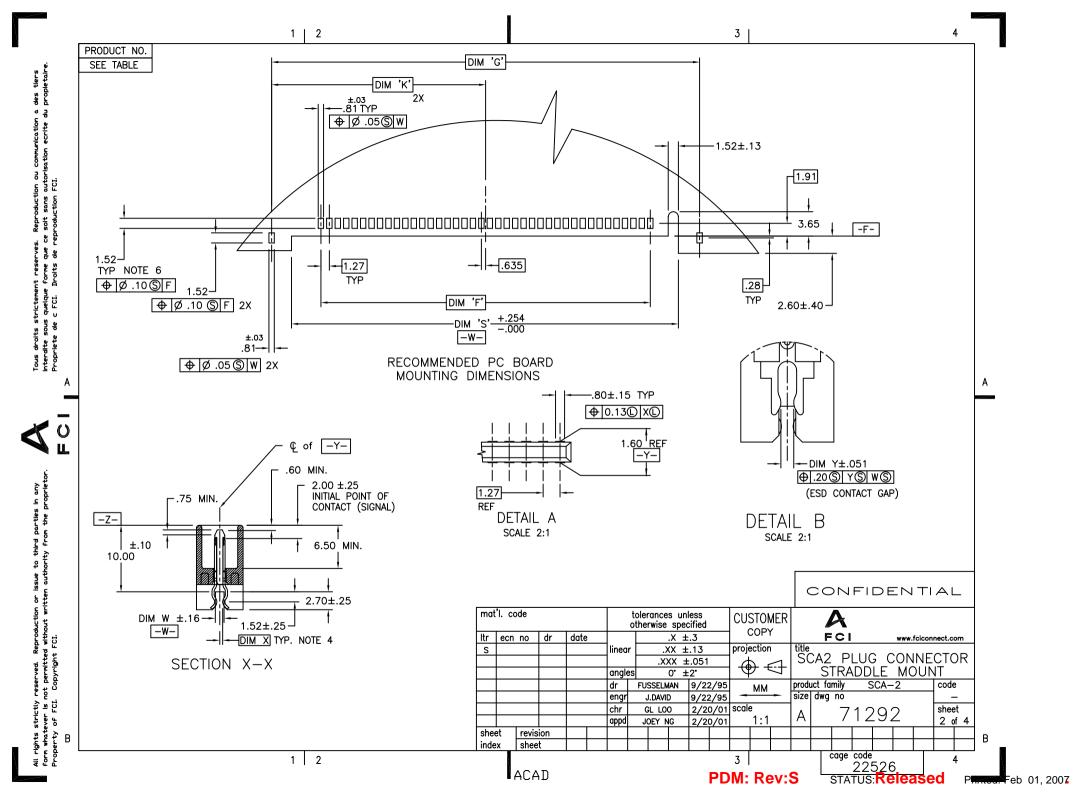


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PRODUCT NO.	NO. POS.	DIM A REF	DIM B	ЫМ С	DIM D	DIM E	DIM F	DIM G	ым н	DIM J	DIM K	POS. N	POS. P	POS. R	DIM S	DIM T	DIM U	DIM V	DIM W	DIM X	DIM Y	PLATING
71292-001 -001S	80	62.15	51.17	55.27	57.87	63.30	49.53	65.36	66.50	66.40	32.68	41	40	80	57.91	57.82	28.88	1.32	1.30	0.44	0.97	NOTE 2
-101S																						NOTE 10
71292-002 -002S	40	36.75	25.77	29.87	32.47	37.90	24.13	39.95	41.10	41.00	19.98	21	20	40	32.52	32.41	16.20	1.32	1.30	0.44	0.97	NOTE 2
-102S																						NOTE 10
71292-003S -103S	80	62.15	51.17	55.27	57.87	63.30	49.53	65.36	66.50	66.40	32.68	41	40	80	57.91	57.82	28.88	1.83	1.83	0.72	1.52	NOTE 2 NOTE 10
71292-004S -104S	40	36.75	25.77	29.87	32.47	37.90	24.13	39.95	41.10	41.00	19.98	21	20	40	32.52	32.41	16.20	1.83	1.83	0.72	1.52	NOTE 2 NOTE 10

NOTES:

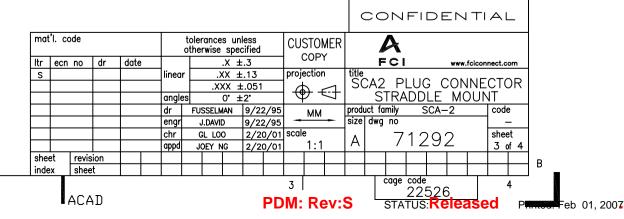
- 1 HOUSING: LCP, UL94V-0 RATED, COLOR: BLACK CONTACTS: PHOSPHOR-BRONZE ESD CONTACT: PHOSPHOR-BRONZE
- 2 PLATING:

CONTACTS: 0.76 μ m (30 μ ") MIN GXT IN CONTACT AREA, 2.54 μ m (100 μ ") MIN TIN-LEAD ON P.C. BOARD LEG, 1.27 μ m (50 μ ") MIN NICKEL UNDERPLATE OVER ENTIRE TERMINAL. ESD CONTACT: 2.54 μ m (100 μ ") MIN TIN-LEAD PLATING W/ 1.27 μ m (50 μ ") NICKEL UNDERPLATE

- (3) MEASURED AT THE FLOOR OF THE CAVITY MEASURED 6mm FROM DATUM -Z-
- (4) APPLIES TO ALL SURFACES OF CONTACT TAILS.
- (5) MAXIMUM BOARD THICKNESS THAT CONNECTOR CAN ACCOMODATE IS DEFINED BY DIM 'V'.
- (6) THESE DIMENSIONS RESULT IN THE CONTACT RESTING IN CENTER OF PAD WIDTH. THESE DIMENSIONS ARE SUBJECT TO CHANGE DEPENDING ON CUSTOMER'S MANUFACTURING PREFERENCES IN PROCESS SOLDER PLACEMENT AND REFLOW.
- (7) DATE CODE IN THIS AREA
- (8) MEASUREMENT MADE AT CENTER OF PART, MAY BE AS LOW AS 6.55. DESIGN TO BE MADE TO ACHIEVE THE NOMINAL DIMENSION ACROSS THE ENTIRE PART.
- (9) DISTANCE MEASURED ACROSS CONTACT MATING SURFACES ALONG EFFECTIVE MATING AREA AND CONTACT MUST BE ABOVE PLASTIC ALONG EFFECTIVE MATING AREA.

1 2

- PLATING: CONTACTS: 0.76μm (30μ") MIN GOLD IN CONTACT AREA, 2.54μm (100μ") MIN TIN-LEAD ON P.C. BOARD LEG, 1.27μm (50μ") MIN NICKEL UNDERPLATE OVER ENTIRE TERMINAL. ESD CONTACT: 2.54μm (100μ") MIN TIN-LEAD PLATING W/ 1.27μm (50μ") NICKEL UNDERPLATE
- 11. PART NUMBERS ENDING IN -0xx or -0xxS or -1xxS ARE MANUFACTURED WITH BRIGHT FINISH TIN-LEAD PLATING IN P.C. BOARD LEG AREA.



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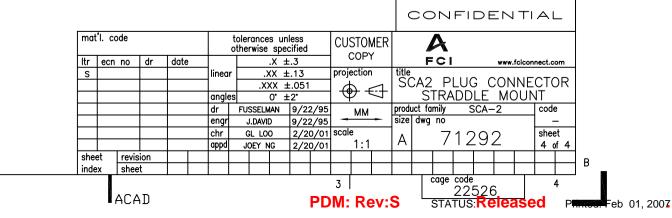
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PRODUCT NO.	NO. POS.	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F	DIM G	ым н	DIM J	ЫМ К	POS. N	POS. P	POS. R	DIM S	ДІМ Т	DIM U	DIM V	DIM W	DIM X	DIM Y	PLATING
71292-001LF -201LF	80	62.15	51.17	55.27	57.87	63.30	49.53	65.36	66.50	66.40	32.68	41	40	80	57.91	57.82	28.88	1.32	1.30	0.44	0.97	NOTE 16 NOTE 12
71292-002LF	40	36 75	25 77	29.87	32 47	37 90	24 13	39 95	41 10	41 00	19.98	21	20	40	32 52	32 41	16.20	1 32	1 30	0 44	0.97	NOTE 12
-202LF 71292-003LF													20	+0	52.52							NOTE 12 NOTE 16
-203LF	80	62.15	51.17	55.27	57.87	63.30	49.53	65.36	66.50	66.40	32.68	41	40	80	57.91	57.82	28.88	1.83	1.83	0.72	1.52	NOTE 12
71292-004LF -204LF	40	36.75	25.77	29.87	32.47	37.90	24.13	39.95	41.10	41.00	19.98	21	20	40	32.52	32.41	16.20	1.83	1.83	0.72	1.52	NOTE 16 NOTE 12
																						NULE 12

NOTES:

- 12. PLATING: CONTACT: $0,76\mu$ m $(30\mu'')$ MIN GOLD IN CONTACT AREA, 2.54 μ m $(100\mu'') - 5.08\mu$ m $(200\mu'')$ TIN (LEAD-FREE) ON P.C. BOARD LEG, 1.27 μ m $(50\mu'')$ MIN. NICKEL UNDERPLATE OVER ENTIRE TERMINAL ESD CONTACT: 2.54 μ m $(100\mu'') -5.08\mu$ m $(200\mu'')$ TIN PLATING (LEAD-FREE) WITH 1.27 μ m $(50\mu'')$ NICKEL UNDERPLATE
- (13) THE HOUSING WILL WITHSTAND EXPOSURE TO 260° C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- (14) THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- 15. PART NUMBERS ENDING IN "LF" MEANS FOR NOTE 14 LEAD FREE IDENTIFICATION. P/N XXXXX-2XXLF IS EQUIVALENT TO PREVIOUS P/N XXXXX-2XX .
- 16. PLATING: CONTACT: 0,76 μ m (30 μ ") MIN GXT IN CONTACT AREA, 2.54 μ m (100 μ ") – 5.08 μ m (200 μ ") TIN (LEAD-FREE) ON P.C. BOARD LEG, 1.27 μ m (50 μ ") MIN. NICKEL UNDERPLATE OVER ENTIRE TERMINAL ESD CONTACT: 2.54 μ m (100 μ ") –5.08 μ m (200 μ ") TIN PLATING (LEAD-FREE) WITH 1.27 μ m (50 μ ") NICKEL UNDERPLATE

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